

Minutes IEEE P802.3cy Greater than 10 Gb/s Electrical Automotive Ethernet PHY TF AdHoc meeting June 15, 2021

Prepared by Natalie Wienckowski

Proposed Agenda:

Title	Presenters(s)	Affiliation(s)
Agenda	Natalie Wienckowski (ad hoc Chair)	General Motors
TF Chair's Comments	Steve Carlson	High Speed Design, Robert Bosch GmbH, Ethernovia
802.3cy Test Fixture Considerations	Chris DiMinico Haysam Kadry	(MC Communications/PHY-SI LLC /Panduit/SenTekse) Ford
P802.3cy To-do list	Natalie Wienckowski	General Motors
Closing Remarks	Steve Carlson	High Speed Design, Robert Bosch GmbH, Ethernovia

See [adhoc webpage for agenda deck and presentations](#)

Agenda/Admin Natalie Wienckowski as ad hoc chair:

Meeting began at 10:04 am ET.

Introductions & Affiliations.

Presented file: [cy Task Force adhoc agenda 06 15 21.pdf](#)

1. Reviewed the Attendance information related to the ad hoc.
2. Displayed patent slide deck and asked if any participant had not read the IEEE-SA Patent Slides slide set, none responded.
Call for Patents was made at 10:10 am Eastern Time, none responded
3. Displayed the IEEE-SA Copyright policy slide and asked if any participant had not read the IEEE copyright slide set, none responded.
4. Displayed the IEEE-SA Participation slide and reviewed it.
5. Reminded participants to indicate full names and employer/affiliation for the meeting minutes.

Instructions for subscribing to the reflector may be found at <http://www.ieee802.org/3/cy/reflector.html>. If you cannot subscribe to the reflector for some reason, and need additional assistance please contact the Task Force chair.

Chair's comments: None at this time.

Presentations/Discussion:

Presentation: [802.3cy Test Fixture Considerations](#) (Chris DiMinico, MC Communications/PHY-SI LLC/Panduit/SenTekse ; Haysam Kadry, Ford)

Chris presented an update for a proposed test fixture in a mated state. It is expected that the test fixture will include a 1" (25.4mm) trace on the PCB. This is in two pieces, each with one part of a connector which are mated together. He suggests a normative requirement on the Host Test Fixture.

There was a question as to whether this requires a specified connector. It could be used if electrical specifications were provided for the connector without having to include mechanical characteristics.

For ch, the PCB IL was added as an informative annex. It is desirable to have this part of the spec in cy.

There would eventually be a complete set of parameters for the Mated Test Fixture, not just IL, if it is agree that this should be included.

Presentation: [P802.3cy To-do list usage](#) (Natalie Wienckowski, General Motors)

The to-do list was reviewed and updated. A new tab has been added with tasks to get to D1.0. Participants are urged to review the list for topics they can support and for missing topics. Please send a message to the reflector with requested changes to the list.

The current list can be found on this page: [To Do spreadsheets](#)

Closing Discussion

We need information on potential noise sources that we need to be immune to around 7 GHz. Also needed is the noise level the PHYs can work with, e.g. 1 mV, 10 mV, etc.

Good meeting everyone!

Please look at the new tab in the to-do list for the Tasks to D1.0 for missing items and items you can contribute to.

Meeting adjourned at 11:59 AM ET.

Attendees (download participant list, email)

First	Last	Affiliation
Chris	DiMinico	MC Communications, PHY-SI, SenTekse / Panduit
Christian	Neulinger	MD Elektronik
Clark	Carty	Cisco
Emilio	Cuesta	TE Connectivity
Eric J	Chang	Intel Corporation
Eric	DiBiaso	TE Connectivity
Erwin	Köependörfer	Leoni Kabel GmbH
George	Zimmerman	CME Consulting / ADI, APL Group, Cisco Systems, CommScope, Marvell, SenTekSe
Harsh	Patel	Molex
Haysam	Kadry	Ford
Hossein	Sedarat	Ethernovia
Istvan	Bakro Nagy	EFFECT Photonics
Jae-yong	Chang	Keysight

First	Last	Affiliation
Jim	Graba	Broadcom
Jonathan	Silvano de Sousa	GG - Austria
Kambiz	Vakilian	Broadcom
Keisuke	Kawahara	FURUKAWA ELECTRIC
Larry	McMillan	Western Digital
Louise	Yi	FIT
Luisma	Torres	KDPOF
Makoto	Nariya	Sony
Manabu	Kagami	NITech (Nagoya Institute of Technology)
Martin	Glanzner	SEI ANTech Europe GmbH
Marty	Gubow	Keysight
Masato	Shiino	Furukawa
Mike	Tu	Broadcom
Natalie	Wienckowski	General Motors
Nobuyasu	Araki	Yazaki
Peter	Wu	Marvell
Ragnar	Jonsson	Marvell
Ryan	Petrarca	TDK
Steve	Carlson	High Speed Design, Robert Bosch GmbH, Ethernovia
Sujan	Pandey	Huawei
Taiji	Kondo	MegaChips
Terry	Little	Foxconn Interconnect Technology
Thomas	Müller	Rosenberger
Toshihiro	Ichimaru	Sumitomo
Yoshihiro	Niihara	Fujikura Ltd.
TOTAL	38	Attendees